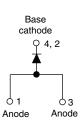


Vishay Semiconductors

Schottky Rectifier, 3.0 A





PRODUCT SUMMARY						
Package	D-PAK (TO-252AA)					
I _{F(AV)}	3.0 A					
V _R	20 V, 30 V, 40 V					
V_F at I_F	0.49 V					
I _{RM}	20 mA at 125 °C					
T _J max.	150 °C					
Diode variation	Single die					
E _{AS}	8 mJ					

FEATURES

- Popular D-PAK outline
- Small foot print, surface mountable
- Low forward voltage drop
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- Compliant to RoHS Directive 2002/95/EC
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 $^\circ\text{C}$

DESCRIPTION

The VS-MBRD320PbF, VS-MBRD330PbF, VS-MBRD340PbF surface mount Schottky rectifier has been designed for applications requiring low forward drop and small foot prints on PC boards. Typical applications are in disk drives, switching power supplies, converters, freewheeling diodes, battery charging, and reverse battery protection.

MAJOR RATINGS AND CHARACTERISTICS										
SYMBOL	CHARACTERISTICS	VALUES	UNITS							
I _{F(AV)}	Rectangular waveform	3.0	A							
V _{RRM}		20 to 40	V							
I _{FSM}	t _p = 5 μs sine	490	A							
V _F	3 Apk, T _J = 125 °C	0.49	V							
TJ		- 40 to 150	°C							

VOLTAGE RATINGS								
PARAMETER	SYMBOL	VS-MBRD320PbF	VS-MBRD330PbF	VS-MBRD340PbF	UNITS			
Maximum DC reverse voltage	V _R	20	30	40	V			
Maximum working peak reverse voltage	V _{RWM}	20	50	40	v			

ABSOLUTE MAXIMUM RATINGS									
PARAMETER	SYMBOL	TEST CONDI	TEST CONDITIONS						
Maximum average forward current	I _{F(AV)}	50 % duty cycle at T_L = 133 °C, re	3.0						
Maximum peak one cycle non-repetitive surge current	I _{FSM}	5 µs sine or 3 µs rect. pulse	Following any rated load	490	А				
		10 ms sine or 6 ms rect. pulse	V _{RRM} applied	75					
Non-repetitive avalanche energy	E _{AS}	T _J = 25 °C, I _{AS} = 1 A, L = 16 mH		8.0	mJ				
Repetitive avalanche current	I _{AR}	Current decaying linearly to zero in 1 μs Frequency limited by T_J maximum V_A = 1.5 x V_R typical		1.0	А				



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ELECTRICAL SPECIFICATIONS									
PARAMETER	SYMBOL	TEST CO	TYP.	MAX.	UNITS				
		3 A	T.I = 25 °C	0.48	0.6	V			
Maximum forward voltage drop	V _{FM} ⁽¹⁾	6 A	1j=25 C	0.58	0.7				
See fig. 1	V FM (1)	3 A	T - 125 °C	0.41	0.49				
		6 A	T _J = 125 °C	0.55	0.625				
Maximum reverse leakage current	I _{RM} ⁽¹⁾	T _J = 25 °C	$V_{\rm B}$ = Rated $V_{\rm B}$	0.02	0.2	mA			
See fig. 2		T _J = 125 °C	V _R = naleu V _R	10.7	20				
Typical junction capacitance	CT	$V_R = 5 V_{DC}$ (test signal range 100 kHz to 1 MHz), 25 °C		189	-	pF			
Typical series inductance	L _S	Measured lead to lead 5 n	5.0	-	nH				
Maximum voltage rate of change	dV/dt	Rated V _R	-	10 000	V/µs				

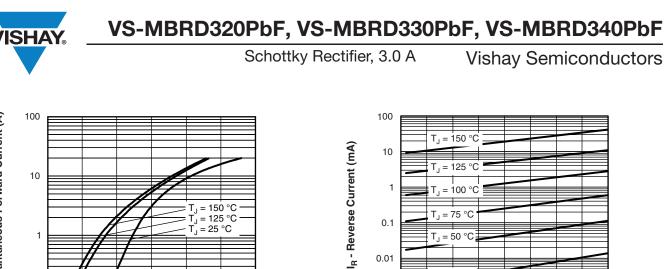
Note

 $^{(1)}\,$ Pulse width < 300 $\mu s,$ duty cycle < 2 %

THERMAL - MECHANICAL SPECIFICATIONS								
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS				
Maximum junction temperature range	T _J ⁽¹⁾		- 40 to 150	°C				
Maximum storage temperature range	T _{Stg}		- 40 to 175	C				
Maximum thermal resistance, junction to case	R _{thJC}	DC operation See fig. 4	6.0	2 0 AA4				
Maximum thermal resistance, junction to ambient	R _{thJA}		80	°C/W				
Approvimeto weight			0.3	g				
Approximate weight			0.01	oz.				
			MBRD320					
Marking device		Case style D-PAK (similar to TO-252AA)	MBRD330					
			MBRD340					

Note

(1) $\frac{dP_{tot}}{dT_J} < \frac{1}{R_{thJA}}$ thermal runaway condition for a diode on its own heatsink



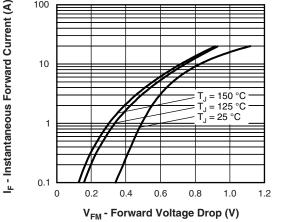
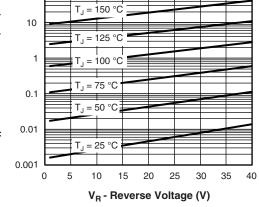
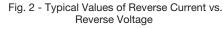


Fig. 1 - Maximum Forward Voltage Drop Characteristics





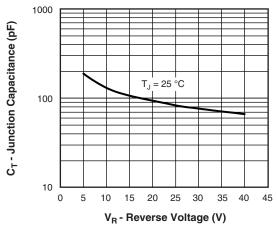


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

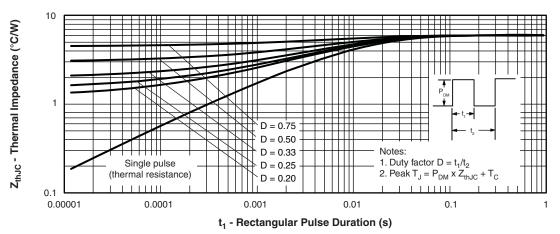


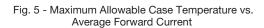
Fig. 4 - Maximum Thermal Impedance ZthJC Characteristics

Schottky Rectifier, 3.0 A



160 Allowable Case Temperature (°C) 150 DC 140 130 Square wave (D = 0.50)120 80 % rated V_R applied 110 See note (1) 100 2 3 4 5 0 1 I_{F(AV)} - Average Forward Current (A)

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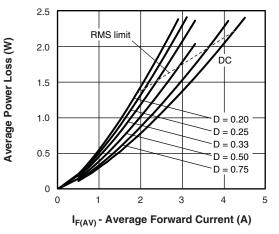


Fig. 6 - Forward Power Loss Characteristics

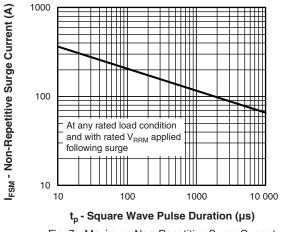


Fig. 7 - Maximum Non-Repetitive Surge Current

Note

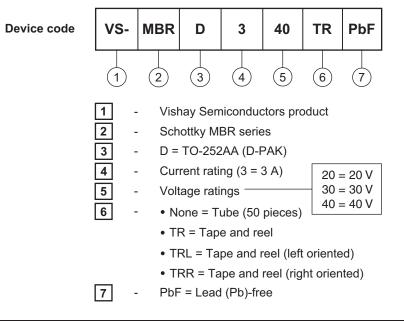
- ⁽¹⁾ Formula used: $T_C = T_J (Pd + Pd_{REV}) \times R_{thJC}$;
- $\begin{array}{l} \mathsf{Pd} = \mathsf{Forward} \ \mathsf{power} \ \mathsf{loss} = \mathsf{I}_{\mathsf{F}(\mathsf{AV})} \ x \ \mathsf{V}_{\mathsf{FM}} \ \mathsf{at} \ (\mathsf{I}_{\mathsf{F}(\mathsf{AV})}/\mathsf{D}) \ (\mathsf{see fig. 6}); \\ \mathsf{Pd}_{\mathsf{REV}} = \mathsf{Inverse} \ \mathsf{power} \ \mathsf{loss} = \mathsf{V}_{\mathsf{R1}} \ x \ \mathsf{I}_{\mathsf{R}} \ (\mathsf{1} \mathsf{D}); \ \mathsf{I}_{\mathsf{R}} \ \mathsf{at} \ \mathsf{V}_{\mathsf{R1}} = \mathsf{80} \ \% \ \mathsf{rated} \ \mathsf{V}_{\mathsf{R}} \end{array}$



Schottky Rectifier, 3.0 A

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ORDERING INFORMATION TABLE



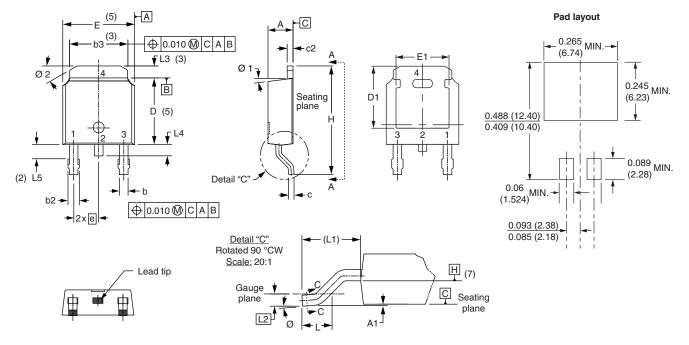
LINKS TO RELATED DOCUMENTS							
Dimensions	www.vishay.com/doc?95016						
Part marking information	www.vishay.com/doc?95059						
Packaging information	www.vishay.com/doc?95033						





D-PAK (TO-252AA)

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES	NOTES	SYMBOL	MILLIN	IETERS	INC	HES	NOTES
STNIBOL	MIN.	MAX.	MIN.	MAX.	NUTES	NOTES	STIVIDUL	MIN.	MAX.	MIN.	MAX.	NOTES
A	2.18	2.39	0.086	0.094			е	2.29	BSC	0.090) BSC	
A1	-	0.13	-	0.005			Н	9.40	10.41	0.370	0.410	
b	0.64	0.89	0.025	0.035			L	1.40	1.78	0.055	0.070	
b2	0.76	1.14	0.030	0.045			L1	2.74	BSC	0.108	REF.	
b3	4.95	5.46	0.195	0.215	3		L2	0.51	BSC	0.020	BSC	
с	0.46	0.61	0.018	0.024			L3	0.89	1.27	0.035	0.050	3
c2	0.46	0.89	0.018	0.035			L4	-	1.02	-	0.040	
D	5.97	6.22	0.235	0.245	5		L5	1.14	1.52	0.045	0.060	2
D1	5.21	-	0.205	-	3		Ø	0°	10°	0°	10°	
E	6.35	6.73	0.250	0.265	5]	Ø1	0°	15°	0°	15°	
E1	4.32	-	0.170	-	3		Ø2	25°	35°	25°	35°	

Notes

⁽¹⁾ Dimensioning and tolerancing as per ASME Y14.5M-1994

(2) Lead dimension uncontrolled in L5

⁽³⁾ Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad

(4) Section C - C dimension apply to the flat section of the lead between 0.13 and 0.25 mm (0.005 and 0.10") from the lead tip

(5) Dimension D, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body

⁽⁶⁾ Dimension b1 and c1 applied to base metal only

⁽⁷⁾ Datum A and B to be determined at datum plane H

⁽⁸⁾ Outline conforms to JEDEC outline TO-252AA

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